

FEATURES

- 2.5V~5.5V Power supply.
- Thermal shutdown Protection.
- Low current shutdown mode
- No capacitors and networks or bootstrap capacitors required
- Low noise during turn-on and turn-off transitions
- Headphone amplifier mode.
- Lead free and green package available. (RoHS Compliant)
- Space Saving Package
-- 8-pin MSOP package.

APPLICATION

- Portable electronic devices
- Mobile Phones
- PDAs

PIN CONFIGURATION

GENERAL DESCRIPTION

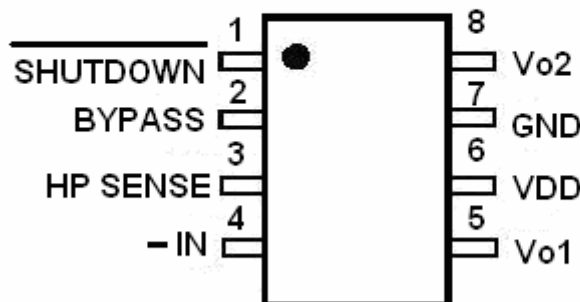
The LY8895 is a 1.4 Watt audio power amplifier. And the LY8895 primarily designed for high quality application in other portable communication device. It is capable of driving 8 Ω speaker load at a continuous average output of 1.4W / 10% distortion (THD+N) from a 5.0V power supply.

A feature of the LY8895 amplifier to switch BTL mode and headphone mode (single-ended) is accomplished using the headphone sense pin. And the LY8895 audio amplifier features low power consumption shutdown mode. It is achieved by driving the shutdown pin with logic low. Besides the LY8895 has an internal thermal shutdown protection feature.

The LY8895 amplifier was designed specifically to provide high quality output power with a minimal amount of external components. The LY8895 does not require output capacitors, and the LY8895 is ideally suited for other low voltage applications or portable electronic devices where minimal power consumption is a primary requirement.

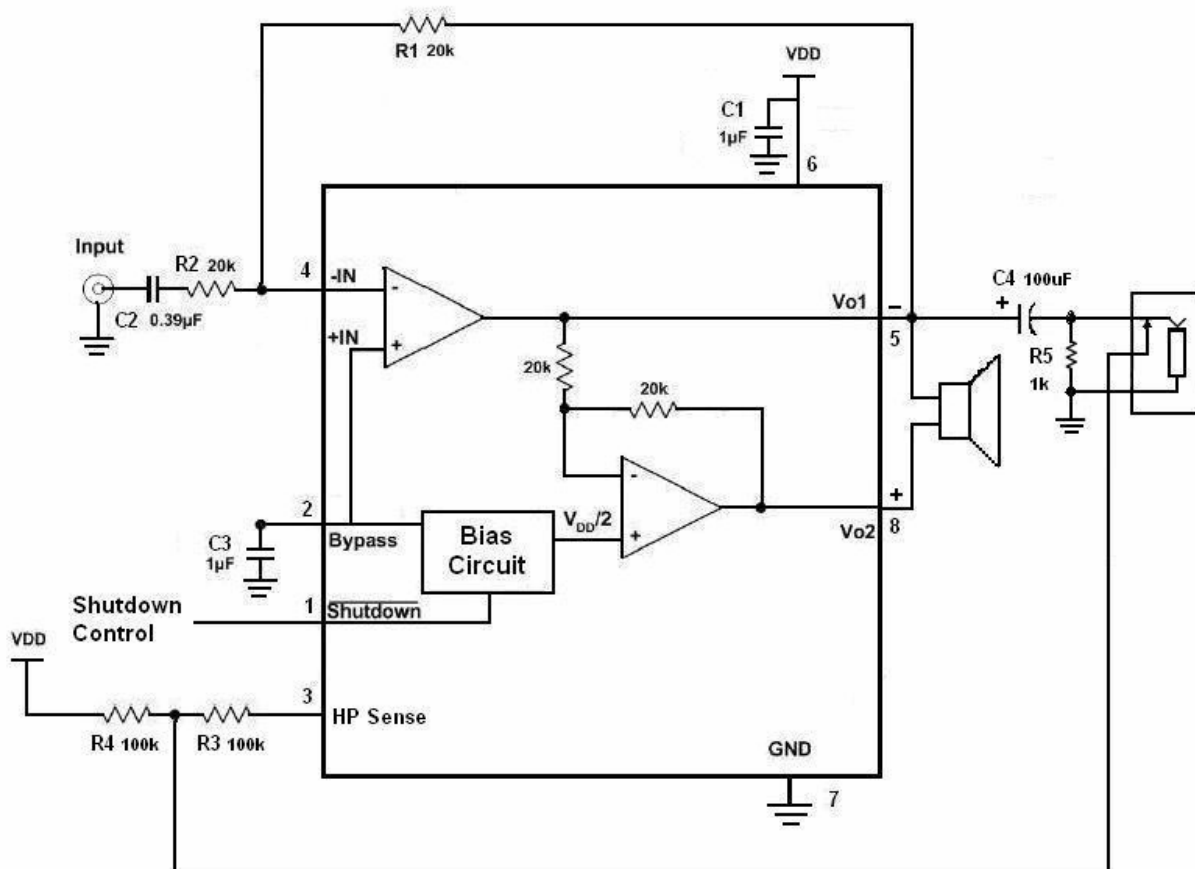
8-PIN MSOP PACKAGE

(TOP VIEW)



PIN DESCRIPTION

SYMBOL	PIN No.	DESCRIPTION
	MSOP	
SHUTDOWN	1	Shutdown the device.(when low level is active the pin)
BYPASS	2	Bypass pin
HP SENSE	3	Headphone sense pin
-IN	4	Negative input
Vo1	5	Negative output
V _{DD}	6	Power supply
GND	7	Ground
Vo2	8	Positive output

APPLICATION CIRCUIT

Figure 1. Audio Amplifier Typical Application Circuit



ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V _{DD}	6.0	V
Operating Temperature	T _A	-40 to 85 (I grade)	°C
Input Voltage	V _I	-0.3V to V _{DD} +0.3V	V
Storage Temperature	T _{STG}	-65 to 150	°C
Power Dissipation	P _D	Internally Limited	W
ESD Susceptibility	V _{ESD}	2000	V
Junction Temperature	T _{JMAX}	150	°C
Soldering Temperature (under 10 sec)	T _{SOLDER}	260	°C

DC ELECTRICAL CHARACTERISTICS (V_{DD}=5V, T_A=25°C)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Power Supply Current	I _{DD}	V _{IN} = 0V, I _o = 0A, No Load	-	3.5	9.0	mA
		V _{IN} = 0V, I _o = 0A, 8Ω Load	-	4.0	10.0	mA
Shutdown Current	I _{SD}	V _{SHUTDOWN} = 0V	-	0.1	2.0	μA
HP Sense high input voltage	V _{IH}		0.8xV _{DD}	-	-	V
HP Sense low input voltage	V _{IL}		-	-	0.2xV _{DD}	V
Wake-up time	T _{WU}	Bypass cap. = 1.0uF	-	176		ms
Output Offset Voltage	V _{OS}		-	7.0	50.0	mV
Output Power	P _o	THD = 10% , f = 1 kHz R _L = 8Ω, HP Sense < 0.2xV _{DD}		1.4		W
		THD = 1% , f = 1 kHz R _L = 8Ω, HP Sense < 0.2xV _{DD}	-	1.0		W
		THD = 1% (max), f = 1kHz, R _L = 32Ω, HP Sense > 0.8xV _{DD}	-	90		mW
Total Harmonic Distortion+ Noise	THD+N	P _o = 0.4 Wrms; f = 1kHz	-	0.13		%
Power Supply Rejection Ratio	PSRR	Vripple = 200mV sine p-p Input terminated with 10Ω to GND	-	62 (f = 217Hz) 66 (f = 1kHz)	-	dB
Thermal Shutdown Temperature	T _{SD}		150	170	190	°C
Shut Down Time	T _{SdT}	8 Ω load		1.0		ms

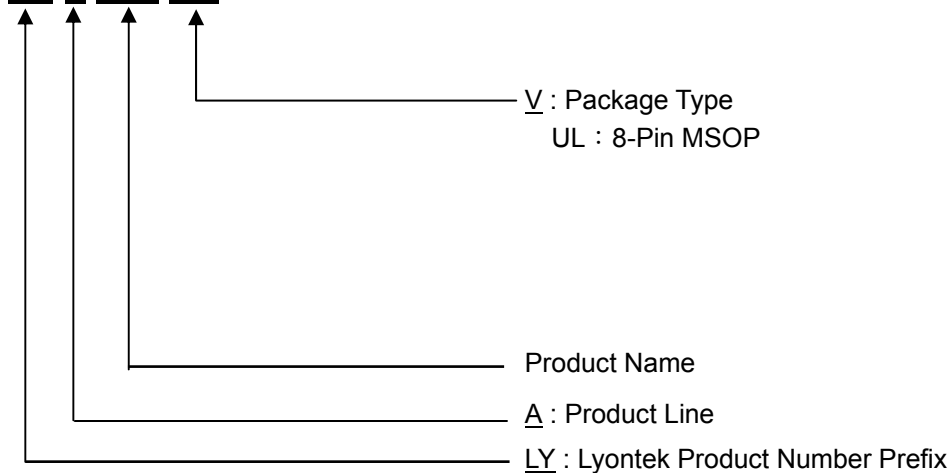


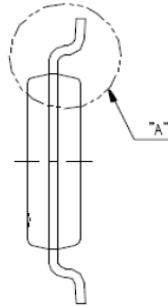
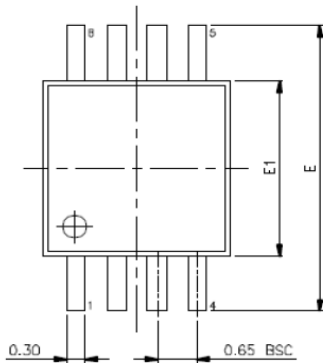
DC ELECTRICAL CHARACTERISTICS (V_{DD}=3V, T_A=25°C)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Power Supply Current	I _{DD}	V _{IN} = 0V, I _o = 0A, No Load	-	3.0	8.0	mA
		V _{IN} = 0V, I _o = 0A, 8Ω Load	-	3.5	9.0	mA
Shutdown Current	I _{SD}	V _{SHUTDOWN} = 0V	-	0.1	2.0	μA
HP Sense high input voltage	V _{IH}		0.8xV _{DD}	-	-	V
HP Sense low input voltage	V _{IL}		-	-	0.2xV _{DD}	V
Output Offset Voltage	V _{OS}		-	7.0	50.0	mV
Wake-up time	T _{WU}		-	114		ms
Output Power	P _o	THD = 10% , f = 1 kHz R _L = 8Ω, HP Sense < 0.2xV _{DD}		0.46		W
		THD = 1% , f = 1 kHz R _L = 8Ω, HP Sense < 0.2xV _{DD}	-	0.375		W
		THD = 1% (max), f = 1kHz, R _L = 32Ω, HP Sense > 0.8xV _{DD}	-	35		mW
Total Harmonic Distortion+ Noise	THD+N	P _o = 0.25 W _{rms} , f = 1kHz	-	0.13	-	%
Power Supply Rejection Ratio	PSRR	V _{ripple} = 200mV sine p-p Input terminated with 10Ω to GND	-	56 (f = 217Hz) 62 (f = 1kHz)	-	dB
Thermal Shutdown Temperature	T _{SD}		150	170	190	°C

ORDERING INFORMATION

LY 8 895 VV



PACKAGE OUTLINE DIMENSION
8 pin 25.6 mil MSOP Package Outline Dimension


SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.10
A1	0.00	—	0.15
A2	0.75	0.85	0.95
D	3.00 BSC		
E	4.90 BSC		
E1	3.00 BSC		
L	0.40	0.60	0.80
L1	0.95 REF		
θ°	0	—	8

UNIT : MM

NOTES:

1. JEDEC OUTLINE : MO-187 AA
2. DIMENSION 'D' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
3. DIMENSION 'E1' DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
4. DIMENSION '0.22' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE '0.22' DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPAC BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07 MM.
5. DIMENSIONS 'D' AND 'E1' TO BE DETERMINED AT DATUM PLANE \square .

